

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention

Elimination of RDL Using Tape Base Flip Chip on Flex for Die
Stacking

Application Number : 10/050507



Confirmation Number: 7687

First Named Applicant: Teck Lee

Attorney Docket Number: MTI-31607

Art Unit: 2813

Examiner: Jack SJ Chen

Search string: (6308525 or 5468995 or 6610559).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6308525	2001-03-27	Imasu et al.		361	783
	2	5468995	1995-11-21	Higgins III		257	697
	3	6610559	2003-08-26	Wang et al.		438	108

Signature

Examiner Name	Date